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9-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
THS4130CD	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	4130C
THS4130CDGN	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	0 to 70	AOB
THS4130CDGNR	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	0 to 70	AOB
THS4130IDGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASO
THS4130IDGKR.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASO
THS4130IDGN	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	-40 to 85	AOC
THS4130IDGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(4130, AOC)
THS4130IDGNR.B	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(4130, AOC)
THS4130IDGNRG4	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	4130
THS4130IDGNRG4.B	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	4130
THS4130IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4130I
THS4130IDR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4130I
THS4130IDRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4130I
THS4130IDRG4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4130I
THS4130IDRG4.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4130I
THS4131CD	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	4131C
THS4131CDGN	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	0 to 70	AOD
THS4131CDGNR	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	0 to 70	AOD
THS4131CDR	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	4131C
THS4131ID	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	41311
THS4131IDGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASP
THS4131IDGKR.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASP
THS4131IDGKRG4	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASP
THS4131IDGKRG4.A	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASP
THS4131IDGKRG4.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASP
THS4131IDGN	Obsolete	Production	HVSSOP (DGN) 8	-	-	Call TI	Call TI	-40 to 85	AOE
THS4131IDGNR	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(4131, AOE)
THS4131IDGNR.B	Active	Production	HVSSOP (DGN) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	(4131, AOE)
THS4131IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	41311



PACKAGE OPTION ADDENDUM

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Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
THS4131IDR.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	4131I

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.